



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: T. UCHIDA, et al.
Application No.: 09/869,347
Filed: SEPTEMBER 7, 2001
For: MATERIALS FOR POLISHING LIQUID FOR METAL,
POLISHING LIQUID FOR METAL, METHOD FOR
PREPARATION THEREOF AND POLISHING METHOD USING
THE SAME
Group AU: 2813
Examiner: L. M. Schillinger
Confirm. No: 4090

SUPPLEMENTAL AMENDMENT**Mail Stop: AMEND – NO FEE**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

February 1, 2007

Sir:

Supplementing the Amendment filed December 18, 2006, which was responsive to the Office Action mailed October 16, 2006, please amend the above-identified application as listed in the following, and as set forth on the following pages:

AMENDMENTS TO THE CLAIMS; and

REMARKS are included following the amendments.